

TAIWAN SEMICONDUCTOR MANUFACTURING CO LTD  
Form 6-K  
January 28, 2019

1934 Act Registration No. 1-14700

**SECURITIES AND EXCHANGE COMMISSION**

**Washington, DC 20549**

**FORM 6-K**

**REPORT OF FOREIGN PRIVATE ISSUER**

**PURSUANT TO RULE 13a-16 OR 15d-16**

**OF THE SECURITIES EXCHANGE ACT OF 1934**

**For the month of January 2019**

**Taiwan Semiconductor Manufacturing Company Ltd.**

**(Translation of Registrant's Name Into English)**

**No. 8, Li-Hsin Rd. 6,**

**Hsinchu Science Park,**

**Taiwan**

**(Address of Principal Executive Offices)**

(Indicate by check mark whether the registrant files or will file annual reports under cover of Form 20-F or Form 40-F.)

Form 20-F

Form 40-F

(Indicate by check mark whether the registrant by furnishing the information contained in this form is also thereby furnishing the information to the Commission pursuant to Rule 12g3-2(b) under the Securities Exchange Act of 1934.)

Yes

No

(If  Yes is marked, indicated below the file number assigned to the registrant in connection with Rule 12g3-2(b):  
82: \_\_\_\_\_.)

**SIGNATURES**

Pursuant to the requirements of the Securities Exchange Act of 1934, the registrant has duly caused this report to be signed on its behalf by the undersigned, thereunto duly authorized.

Taiwan Semiconductor Manufacturing Company Ltd.

Date: January 28, 2019

By /s/ Lora Ho  
Lora Ho  
Senior Vice President & Chief Financial Officer

Clarification of media reports

TSMC has discovered that a shipment of certain chemical used in the manufacturing process deviated from specifications and caused wafers to have lower yields. We are carefully investigating the root cause and are communicating with affected customers regarding remedial actions.

We estimate that most of the affected wafers can be made up in the First Quarter, with the remainder made up in the Second Quarter. Based on our current estimate, TSMC should be able to meet its First Quarter guidance given on January 17, 2019.